L Number	Hits	Search Text	DB	Time stamp
1	2915	wafer adj alignment	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:14
8	110226	light same measurement	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:15
22	0	mems and ((wafer adj alignment) and (light same measurement))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:15
15	438	(wafer adj alignment) and (light same measurement)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:16
-	16291	dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:14
-	49	(wafer adj bonding and (mems or micro adj electro adj mechanical)) and dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 10:58
-	299	wafer adj bonding and mems	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:09
-	46	dicing and (wafer adj bonding and mems)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:11
-	3	("6452238").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:17
-	5	("4873871" | "6310371" | "6326682" | "6180989" | "6369931").PN.	USPAT	2003/06/12 11:16
-	0	6452238.URPN.	USPAT	2003/06/12 11:17
-	972	wafer adj orientation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:17
-	24138	mems	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/23 12:15
-	7	(wafer adj orientation) and mems	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:18
-	327	wafer adj bonding and (mems or micro adj electro adj mechanical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:20

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–	2475	wafer adj bonding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:21
–	299	mems and (wafer adj bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:21
–	259	dicing and (wafer adj bonding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:21
–	46	mems and (dicing and (wafer adj bonding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:23
–	275443	packaging	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:23
–	3187	mems and packaging	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:23
–	137	dicing and (mems and packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 11:23
–	2	("6521477").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 12:08
–	46	mems and die and second adj wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 12:27
–	12	mems adj die and holder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 12:27
–	16	bonding and holder and mems and second adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 17:18
–	76	mems and dicing and aligning	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/12 17:18
–	0	cantiliever adj beam and packaging and holder and dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/14 05:31
–	0	cantiliever adj beam and dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/14 05:31

-	112	cantilever adj beam and dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/14 05:38
-	67	mems adj die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/14 05:38
-	4	5494698.URPN.	USPAT	2003/06/14 05:50